

Product Change Notification / RMES-02FUOC874

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04-Mar-2022

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4886 Final Notice: Qualification of CEL-8240 GS as a new mold compound and 84-1 LIMIS R4 die attach material for selected 11AAxxx and 11LCxxx device families available in 3L TO-92 package assembled at CRTK assembly site.

Affected CPNs:

RMES-02FUOC874_Affected_CPN_03042022.pdf RMES-02FUOC874_Affected_CPN_03042022.csv

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CEL-8240 GS as a new mold compound and 84-1 LIMIS R4 die attach material for selected 11AAxxx and 11LCxxx device families available in 3L TO-92 package assembled at CRTK assembly site.

Pre and Post Change Summary:

		Pre Change	Post Change					
Assembly Site		Greatek Electronic Inc. (GTK)	Cirtek Electronics Corporation (CRTK)					
Wire Material		Au	Au					
Die Attach Material		CRM1076DJ-G	84-1LMISR4					
Molding Compound Material		G600F	CEL-8240 GS					
	Material*	CDA194	A194					
Lead frame	Lead lock (Locking Holes)	No	No					
Design		See attached Pre and Post change comparisor						

Note: * C194, A194 or CDA194 Lead frame material are the same, it is just a MCHP internal labelling difference.

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve productivity and on-time delivery performance by qualifying CEL-8240 GS as a new mold compound and 84-1 LIMIS R4 die attach material at CRTK assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date: April 8, 2022 (date code: 2215)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2021					>	March 2022					April 2022			
Workweek	4	4	4	4	4		1	1	1	1	1	1	1	1	1
	5	6	7	8	9		0	1	2	3	4	5	6	7	8
Initial PCN Issue	v														
Date	Х														
Qual Report							V								
Availability							Х								

Final PCN Issue Date				Х					
Estimated Implementation							>		
Date							Х		

Method to Identify Change: Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:November 03, 2021: Issued initial notification.

March 4, 2022: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 17, 2022.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-02FUOC874_Qual Report.pdf PCN_RMES-02FUOC874_Pre and Post Change_Summary.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

11LC010-E/TO

11LC010-I/TO

11AA010-I/TO

11LC020-E/TO

11LC020-I/TO

11AA020-I/TO

11LC040-E/TO

11LC040-I/TO

11AA040-I/TO

11LC080-E/TO

11LC080-I/TO

11AA080-I/TO

11LC160-E/TO

11LC160-I/TO

11AA160-I/TO

11LC161-I/TO

11AA161-I/TO

Date: Thursday, March 03, 2022